

# **Electronic Acknowledgement Receipt**

<b>EFS ID:</b>	1471190
<b>Application Number:</b>	10598514
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	6698
<b>Title of Invention:</b>	MULTIPLE STACKED DIE WINDOW CSP PACKAGE AND METHOD OF MANUFACTURE
<b>First Named Inventor/Applicant Name:</b>	Chuen Khiang WANG 93/06/2007 THM L-04 20060003 100 3514
<b>Customer Number:</b>	7055 01 FC:1617 145.00 5P
<b>Filer:</b>	Daniel Brian Moon/Ramon Linsangan
<b>Filer Authorized By:</b>	Daniel Brian Moon
<b>Attorney Docket Number:</b>	P26634
<b>Receipt Date:</b>	29-JAN-2007
<b>Filing Date:</b>	
<b>Time Stamp:</b>	16:01:23
<b>Application Type:</b>	U.S. National Stage under 35 USC 371

### **Payment information:**

Submitted with Payment	yes
Payment was successfully received in RAM	\$130
RAM confirmation Number TRANSACTION DATE: 05/06/2007 11:01 AM	362
Deposit Account INTEREST SUBSIDIES TRUST FUND	-130.00 30

## **File Listing:**

<b>Document Number</b>	<b>Document Description</b>	<b>File Name</b>	<b>File Size(Bytes)</b>	<b>Multi Part/.zip</b>	<b>Pages (if appl.)</b>
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